

ISO 1043

**UL 746B** 

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## Zytel® HTNFR55G50NHLW BK046

### HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimize performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTNFR55G50NHLW BK046 is a 50% glass reinforced, flame retardant high performance polyamide resin with improved flow and low warpage in structural applications requiring good surface appearance. It uses a non-halogenated flame retardant.

PA-GF50FR(40)

## Product information Resin Identification

Part Marking Code	>PA-GF50FR(40)<		ISO 11469
Part Marking Code	>PPA-GF50FR<		SAE J1344
ISO designation	ISO 16396-PA,G		
Rheological properties	dry/cond.		
Viscosity number	70/*	cm <sup>3</sup> /g	ISO 307, 1628
Moulding shrinkage, parallel	0.1/-	%	ISO 294-4, 2577
Moulding shrinkage, normal	0.2/-	%	ISO 294-4, 2577
Flow length	165/*	mm	,
Flow length - pressure	100/*	MPa	
Flow length - width/thickness	1/*	mm	
Typical mechanical properties	dry/cond.		
Tensile modulus	18000/19100	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	200/176	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	1.6/1.3	%	ISO 527-1/-2
Flexural modulus	17000/-	MPa	ISO 178
Flexural strength	310/-	MPa	ISO 178
Charpy impact strength, 23°C	50/-	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	13/-	kJ/m²	ISO 179/1eA
Poisson's ratio	0.33/0.33		
Thermal properties	dry/cond.		
Melting temperature, 10°C/min	296/*	°C	ISO 11357-1/-3
Glass transition temperature, 10 °C/min	110/-	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	215/*	°C	ISO 75-1/-2
Coefficient of linear thermal expansion	13/*	E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Coefficient of linear thermal expansion (CLTE),	38/*	E-6/K	ISO 11359-1/-2
normal			
RTI, electrical, 0.4mm	65	°C	UL 746B
RTI, electrical, 0.75mm	65	°C	UL 746B

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65

65

65

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RTI, electrical, 1.5mm

RTI, electrical, 3.0mm

RTI, impact, 0.4mm



RTI, impact, 0.75mm RTI, impact, 1.5mm RTI, impact, 3.0mm RTI, strength, 0.4mm RTI, strength, 0.75mm RTI, strength, 1.5mm RTI, strength, 3.0mm TGA curve	65 65 65 65 65 /* 65 available	°C °C °C °C °C	UL 746B UL 746B UL 746B UL 746B UL 746B UL 746B UL 746B ISO 11359-1/-2
Flammability	dry/cond.		
Burning Behav. at 1.5mm nom. thickn. Thickness tested UL recognition Burning Behav. at thickness h Thickness tested UL recognition FMVSS Class	V-0/* 1.5/* yes/* V-0/* 0.4/* yes/* DNI	class mm class mm	IEC 60695-11-10 IEC 60695-11-10 UL 94 IEC 60695-11-10 IEC 60695-11-10 UL 94 ISO 3795 (FMVSS 302)
Electrical properties	dry/cond.		
Comparative tracking index Dielectric Constant, 1 GHz Dielectric Constant, 23°C, 10 GHz Dissipation Factor, 1 GHz	600/- 4.3/- 4.4/-	E-4	IEC 60112 ASTM D 2520 B ASTM D 2520 B / IPC- TM-650 ASTM D 2520 B
Dissipation Factor, 23°C, 10 GHz	122/-	E-4	ASTM D 2520 B / IPC- TM-650
Physical/Other properties	dry/cond.		
Water absorption, Immersion 24h Density	0.6/* 1650/-	% kg/m³	Sim. to ISO 62 ISO 1183
Injection			
Drying Recommended Drying Temperature Drying Time, Dehumidified Dryer Processing Moisture Content Melt Temperature Optimum Min. melt temperature Max. melt temperature Mold Temperature Optimum Min. mould temperature Max. mould temperature Ejection temperature	10 6 - ≤0 30 29 3 10 12 14	es 00 °C -8 h 0.1 % 05 °C 95 °C 15 °C 30 °C 20 °C 40 °C 36 °C	

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## Zytel® HTNFR55G50NHLW BK046

### HIGH PERFORMANCE POLYAMIDE RESIN

### Characteristics

Processing Injection Moulding

Additives Flame retardant, Non-halogenated/Red phosphorous free flame retardant

Special characteristics Flame retardant

Additional information

Injection molding For molding machine components, use corrosion resistant and wear resistant

steel. For details please contact our representative. Limit the residence time of

the resin in the machine. Use proper protective equipment and adequate

ventilation.

### **Automotive**

OEM STANDARD ADDITIONAL INFORMATION

Renault-Nissan UB25c, No Spec, Special Part Approval, See

Your CE Account Manager.

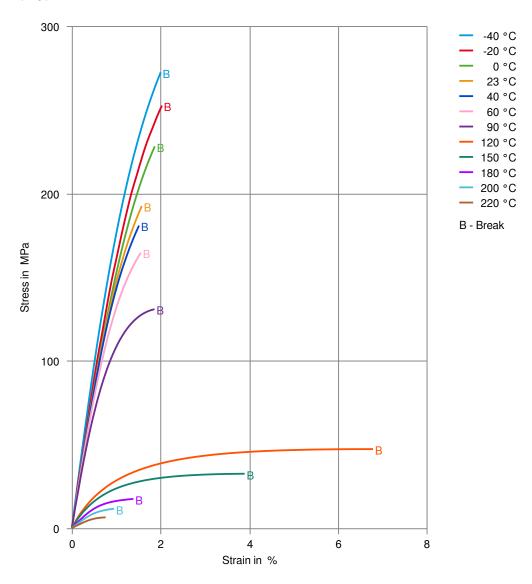
Stellantis B62 0300 / 61/223E-218M/C1/C4 Technical Black

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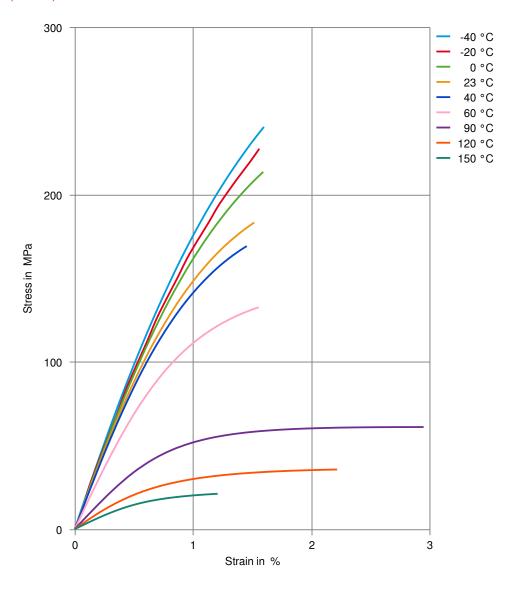
### Stress-strain (dry)



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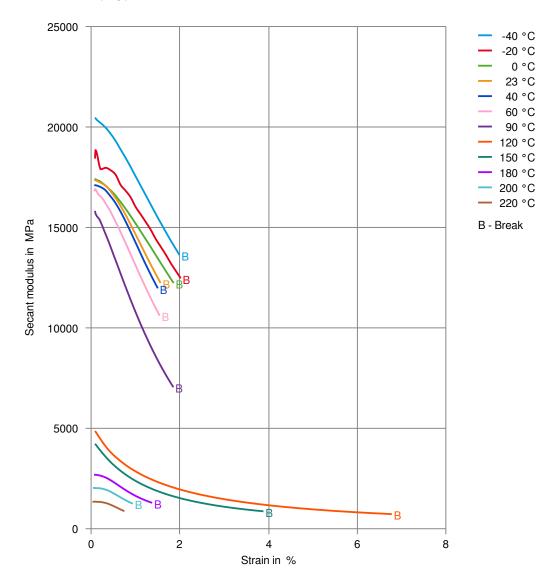
### Stress-strain (cond.)



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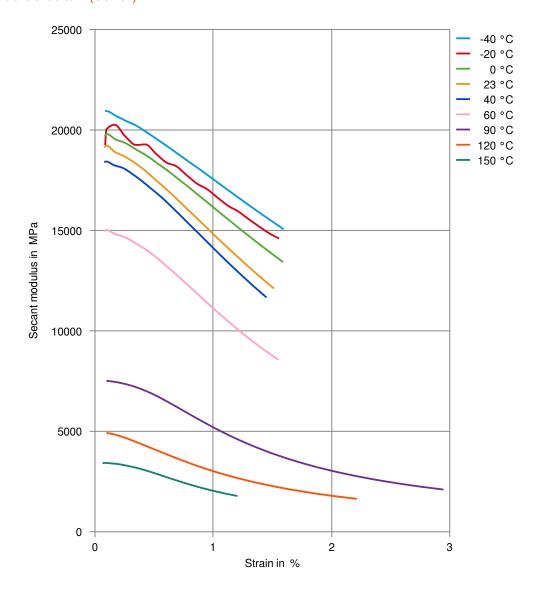
### Secant modulus-strain (dry)



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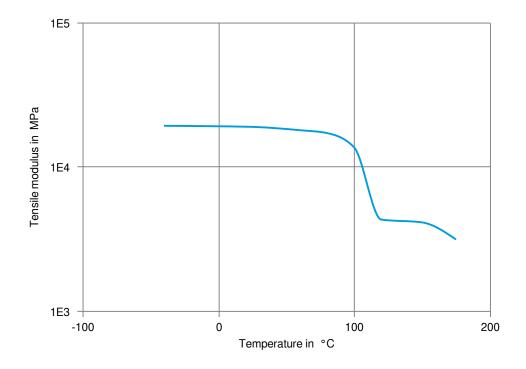
### Secant modulus-strain (cond.)



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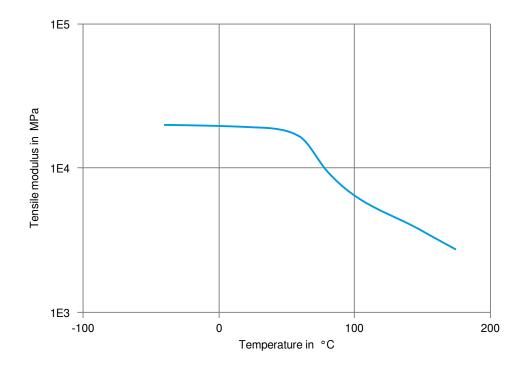
Tensile modulus-temperature (dry)



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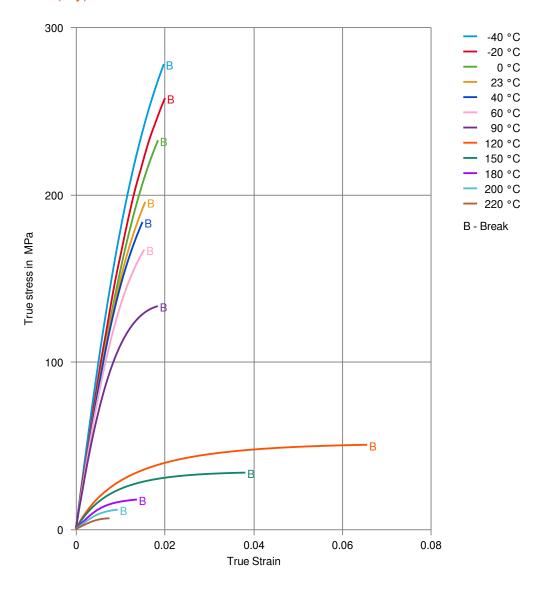
Tensile modulus-temperature (cond.)



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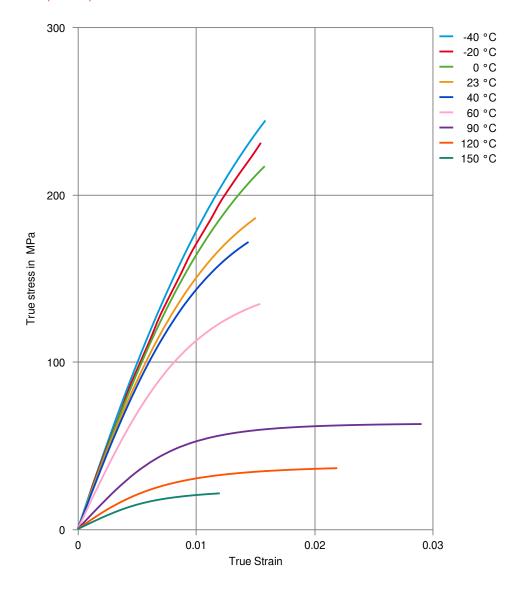
### True stress-strain (dry)



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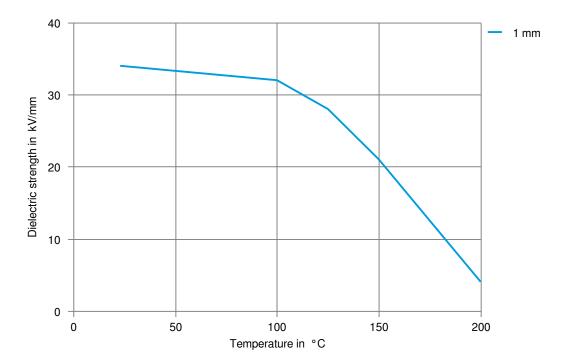
### True stress-strain (cond.)



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Dielectric strength - temperature (dry)



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